ON Semiconductor

INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION # 20133

Generic Copy

Issue Date: 19-Jul-2013

TITLE: Material Change on Leadframe and Mold resin of SOIC8 as to Flash memory LE25U40CMC series.

PROPOSED FIRST SHIP DATE: 19-Nov-2013

AFFECTED CHANGE CATEGORY(S): Material of Leadframe and Mold resin

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or
<Hiroshi.Motegi@onsemi.com> or <Yujiro.Yoshida@onsemi.com>

NOTIFICATION TYPE:

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

The purpose of this change is to increase the units in the Leadframe for enhancement of the manufacturing process with greater efficiency & productivity. The Mold resin is changed at the same time.

The package outline dimension has no change. And the characteristic and quality also will have no impact.
In addition, there are no changes such as the mark on the package. This change can be traced by package marking lot number.

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QUALIFICATION PLAN:
Estimated Date for Qualification Completion: Sep/31/2013
Samples should be available after completion of Qualification.

Reliability Test item and Condition

HTOL	TA = 125°C for 1000 hrs
HTSL	TA = 150°C for 1000 hrs
*THB	85°C/85% RH for 1000 hrs
*AC	121°C/100% RH 2.03×105Pa for 96hrs
*TC	-65°C to +150°C for 500 cycles

Note: The test items with "*" mark are put into operation after the reflow soldering (at 255'C for 30s, 3times)

List of affected General Parts:

LE25U40CMC-AH
LE25U40CMCS00-AH

List of affected Customer Specific Parts:

LE25U40CMCS01-AH
LE25U40CMCS02-AH
LE25U40CMCS03-AH
LE25U40CMCQ00-AH
LE25U40CMCQ02-AH
LE25U40CMCQ03-AH
LE25U40CMCQ04-AH
LE25U40CMCQ05-AH
LE25U40CMCQ06-AH
LE25U40CMCQ07-AH
LE25U40CMCQ08-AH
LE25U40CMCQ09-AH